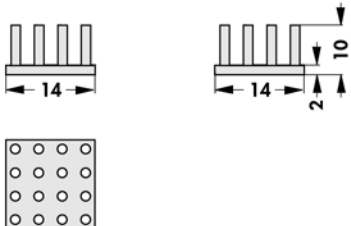
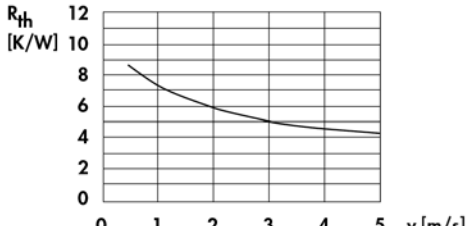
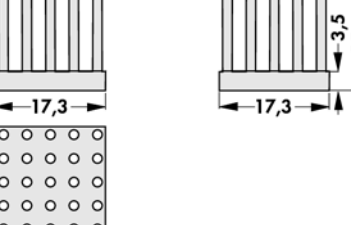
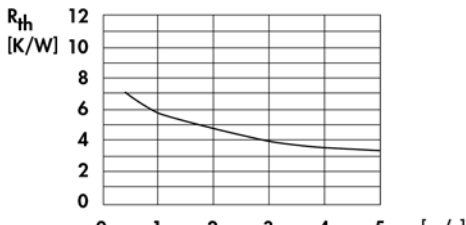
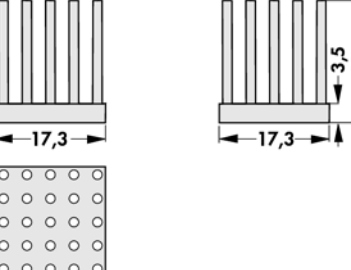
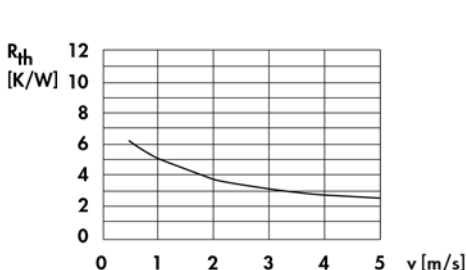
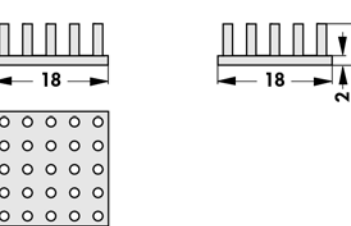
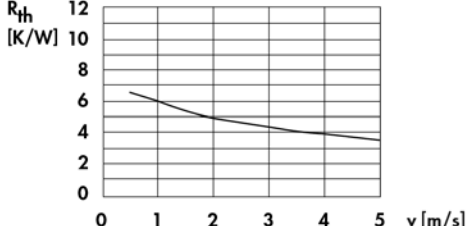
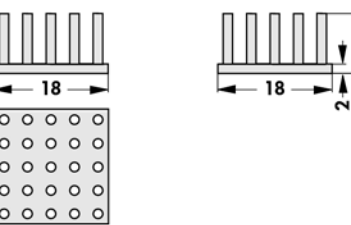
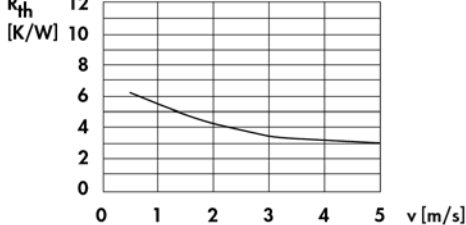
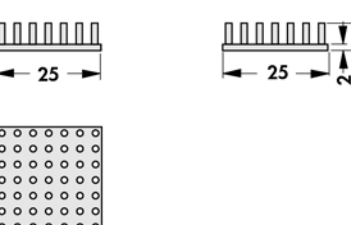
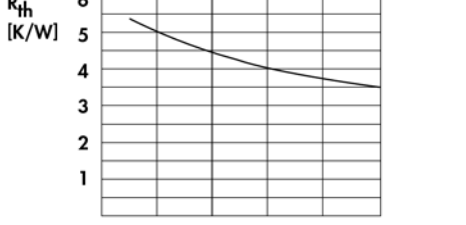
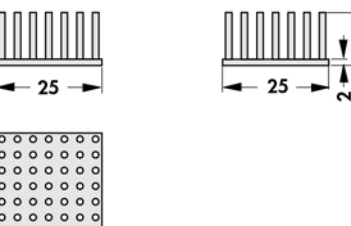
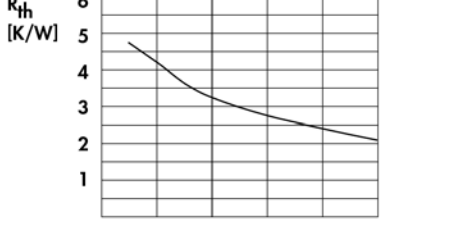


Pin heatsinks

art. no. ICK S 14 x 14 x 10 WLF ... 14 x 14 weight: 1.9 g		
art. no. ICK S 17 x 17 x 15 WLF ... 17 x 17 weight: 4.7 g		
art. no. ICK S 17 x 17 x 20 WLF ... 17 x 17 weight: 5.6 g		
art. no. ICK S 18 x 18 x 6,5 WLF ... 18 x 18 weight: 2.5 g		
art. no. ICK S 18 x 18 x 10 WLF ... 18 x 18 weight: 3.1 g		
art. no. ICK S 25 x 25 x 6,5 WLF ... 25 x 25 weight: 4 g		
art. no. ICK S 25 x 25 x 12,5 WLF ... 25 x 25 weight: 6 g		

B 21

Thermal conduct. foil WLFT 404/405 → E 5
Thermal conductive glue → E 15
Thermal conductive paste → E 13
Processor overview → B 2 - 7

SMD-heatsinks → B 37 - 39
Mounting material for semiconduct. → E 35 - 39
Hole pattern → A 21
Technical introduction → A 2 - 7